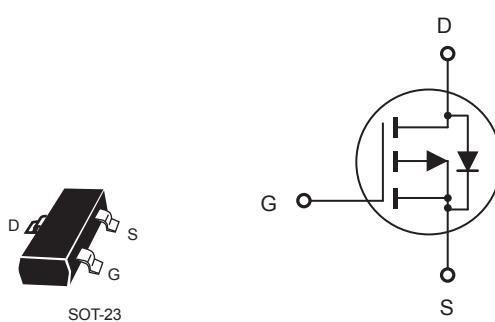


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FEATURES

- -20V, -3.8A, $R_{DS(ON)} = 55\text{m}\Omega$ @ $V_{GS} = -4.5\text{V}$.
 $R_{DS(ON)} = 62\text{m}\Omega$ @ $V_{GS} = -2.5\text{V}$.
- High dense cell design for extremely low $R_{DS(ON)}$.
- Rugged and reliable.
- Lead free product is acquired.
- SOT-23 package.



ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	-3.8	A
Drain Current-Pulsed ^a	I_{DM}	-15.2	A
Maximum Power Dissipation	P_D	1.25	W
Operating and Store Temperature Range	T_J, T_{Stg}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient ^b	$R_{\theta JA}$	100	$^\circ\text{C/W}$

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Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -20\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 12\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -12\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
On Characteristics^c						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = -250\mu\text{A}$	-0.4		-1.0	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -4.5\text{V}, I_D = -2.4\text{A}$		39	55	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}} = -5\text{V}, I_D = -2.4\text{A}$		47	62	$\text{m}\Omega$
Dynamic Characteristics^d						
Input Capacitance	C_{iss}	$V_{\text{DS}} = -10\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		965		pF
Output Capacitance	C_{oss}			200		pF
Reverse Transfer Capacitance	C_{rss}			155		pF
Switching Characteristics^d						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -10\text{V}, I_D = -3.8\text{A}, V_{\text{GS}} = -4.5\text{V}, R_{\text{GEN}} = 3\Omega$		15	30	ns
Turn-On Rise Time	t_r			10	20	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			40	80	ns
Turn-Off Fall Time	t_f			13	26	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = -10\text{V}, I_D = -3.8\text{A}, V_{\text{GS}} = -4.5\text{V}$		13	17	nC
Gate-Source Charge	Q_{gs}			2.5		nC
Gate-Drain Charge	Q_{gd}			3		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current ^b	I_S				-1	A
Drain-Source Diode Forward Voltage ^c	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = -0.42\text{A}$			-1.2	V

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Surface Mounted on FR4 Board, $t < 5 \text{ sec}$.
- c.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- d.Guaranteed by design, not subject to production testing.